錫膏 Solder Paste

印刷用

合金組成 Alloy system	型　號 Product code	熔點(℃) Melting point	粒 徑 (μm) Powder particle size	助焊劑含量(%) Flux content	黏　度 Viscosity Pa·s	用途、特性 Suitable use・Feature
Sn/Ag/Cu	SN96CI PF-32J FMQ	217	45—20	11.1	190	印刷性佳，可抑制印刷時的粘度變化 Good printing performance. Stabilized viscosity is obtainable under continuous printing
	SN97C PF-31N FMQ	218-219		10.9	190	
	SN97C PF-37 SFMQ		38—10	10.8	190	CSP用，最大對應到0.23mm Suitable for CSP Stencil. Max size: 0.23 mm dia.
Sn/Cu+Ni	SN100C PF-25 FMQ	227	45—20	10.7	185	印刷性佳，可預防加熱時坍塌 Good printing performance. Prevent dump formation when heated.
Sn/Ag/Cu/Bi	LF-C2 PF-39 FMQ	208-213		10.8	185	印刷性焊錫性佳，可防止加熱時坍塌 Good printing performance & solderability. Prevent dump formation when heated.
Sn/Ag/In/Bi	LF-SA PF-5 FMQ	202-214		11.5	180	黏度穩定，無錫珠 Prevent the formation of solder ball. Stabilized viscosity
	SN88 PF-51 FMQ	198-210		11.5	180	無坍塌，連續印刷性佳 Obtainable longer tackiness under continuous printing. Prevent dump formation when heated
Sn/Ag	SN96 PF-36 AMQ	221	53—25	11.8	190	印刷性良好 Good printing performance.
Sn/Sb	95A PF-35 AMQ	236-243		11.6	185	印刷性良好 Good printing performance.
Sn/Zn	LF-Z1 PF-14 FMQ	199	45—20	12.0	160	可使用一般迴峰焊，耐久性佳，抑制錫珠之發生 Reflow solderable in air atmosphere. Prevent the formation of solder ball. Stabilized viscosity.

100 Pin(0.5mm pitch)QFP
reflow soldered with SN96CI

點焊(針筒包裝)

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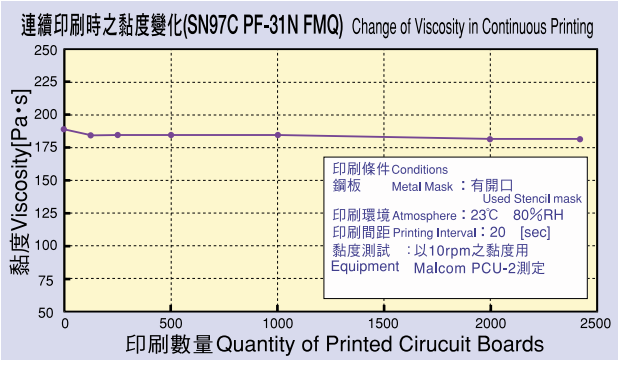
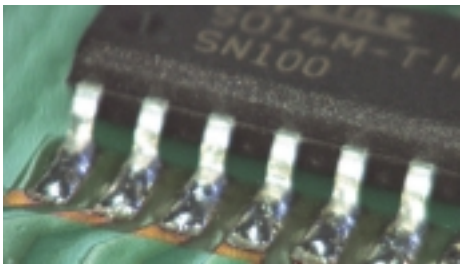
Sn/Ag/Cu	SN96CI RMA FDQ M-21	217	45—20	適急速加熱 Suitable for rapid heating.
	SN96CI RMA FDQ H-1			射出安定、適急速加熱 Stable dispensing. Suitable for rapid heating.
	SN97C RMA FDQ M-21	218—219		適急速加熱 Suitable for rapid heating
	SN97C RMA FDQ H-1			射出安定、適急速加熱 Stable dispensing. Suitable for rapid heating
Sn/Cu+Ni	SN100C RMA FDQ H-1	227		
Sn/Ag	SN96 RMA FDQ H-1	221		

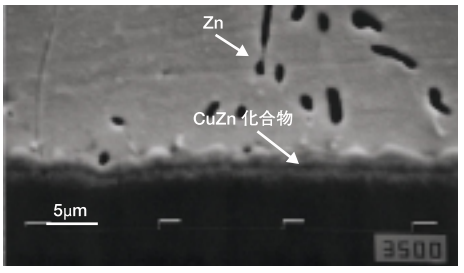


■迴焊用LF-Z1 PF-14 FMQ for Reflow Soldering

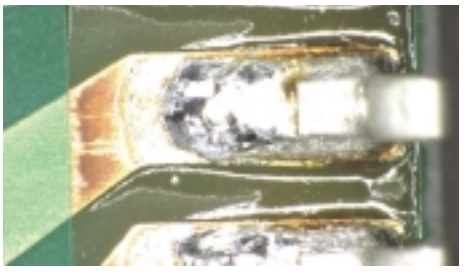
焊錫接合後殘渣無龜裂現象。熱衝擊後焊錫界面無白色氧化物。
(Crack-free at its residue)　(No white oxide on the soldered board after thermal cycle test.)



焊接後之外觀
After reflow soldered



焊錫接合部之界面
Interface of soldered joint



熱衝擊測試後 -25/+125℃各30min. 1000次循環
After thermal cycle test

■無鉛焊錫之參考溫度曲線

最適合的溫度曲線，因基板及迴焊爐設備之性能而多少不同。請依使用的基板與迴焊爐設備，確認實際的溫度曲線。

The optimum reflow profile is to some extent dependent on the characteristics of the board and the capability of the reflow oven. The thermal profile below has been found to work in the Nihon Superior laboratory and could be used a starting point in optimizing the profile for a particular board and oven.